



## Dual P-Channel 20-V (D-S) MOSFET

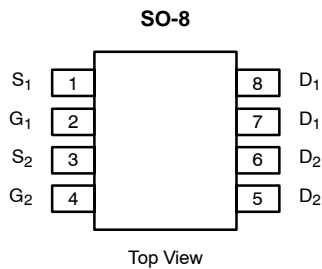
PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
-20	0.019 @ $V_{GS} = -10$ V	-8.4
	0.031 @ $V_{GS} = -4.5$ V	-6.7

### FEATURES

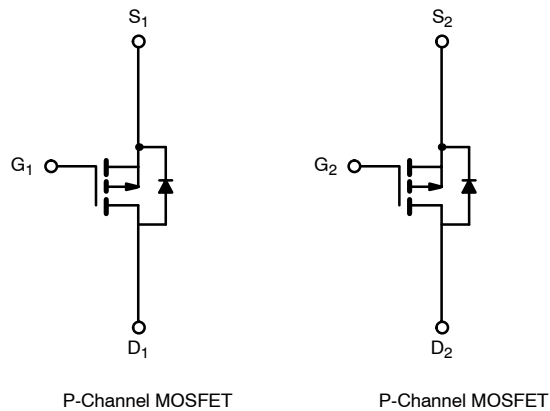
- TrenchFET® Power MOSFET
- 100%  $R_g$  Tested

### APPLICATIONS

- Load Switching
  - Computer
  - Game Systems
- Battery Switching
  - 2-Cell Li-Ion



Ordering Information: Si4943BDY—E3  
Si4943BDY-T1—E3 (with Tape and Reel)



ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)					
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	-20		V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$			
Continuous Drain Current ( $T_J = 150^\circ\text{C}$ ) <sup>a</sup>	$I_D$	$T_A = 25^\circ\text{C}$	-8.4	-6.3	A
		$T_A = 70^\circ\text{C}$	-6.7	-5.1	
Pulsed Drain Current	$I_{DM}$	-30			
Continuous Source Current (Diode Conduction) <sup>a</sup>	$I_S$	-1.7	-0.9		
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25^\circ\text{C}$	2.0	1.1	W
		$T_A = 70^\circ\text{C}$	1.3	0.7	
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	$t \leq 10$ sec	46	62.5	$^\circ\text{C/W}$
		Steady State	85	110	
Maximum Junction-to-Foot (Drain)	$R_{thJF}$	26	35		

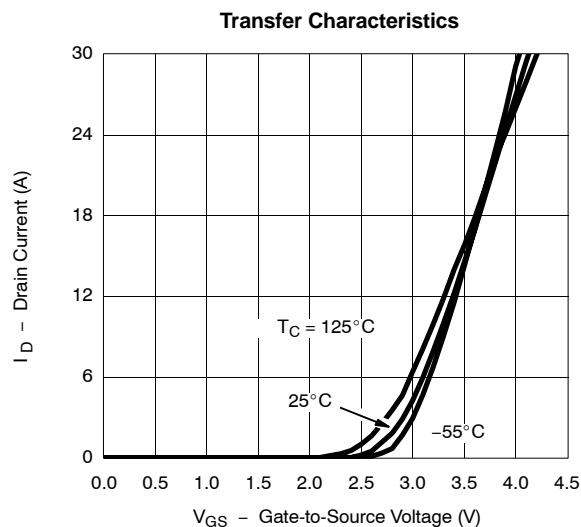
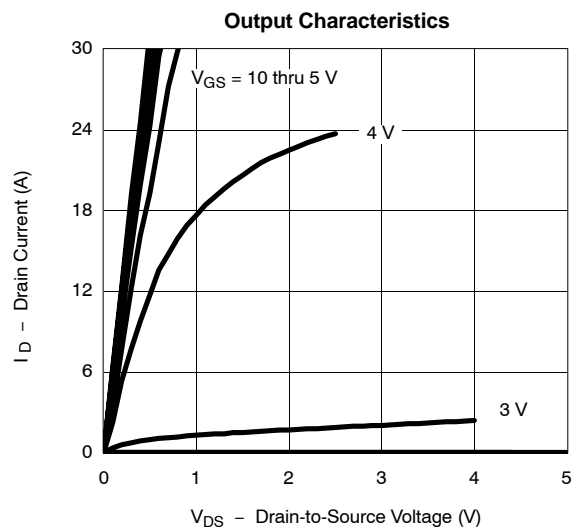
Notes  
a. Surface Mounted on 1" x 1" FR4 Board.

**SPECIFICATIONS (T<sub>J</sub> = 25 °C UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA	-1		-3	V
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V			-1	μA
		V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			-5	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = -5 V, V <sub>GS</sub> = -10 V	-30			A
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -8.4 A		0.016	0.019	Ω
		V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -6.7 A		0.026	0.031	
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -8.4 A		20		S
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = -1.7 A, V <sub>GS</sub> = 0 V		-0.75	-1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = -5 V, I <sub>D</sub> = -8.4 A		17	25	nC
Gate-Source Charge	Q <sub>gs</sub>			5		
Gate-Drain Charge	Q <sub>gd</sub>			6.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	6	12	18	Ω
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10 V, R <sub>L</sub> = 10 Ω I <sub>D</sub> ≅ -1 A, V <sub>GEN</sub> = -10 V, R <sub>g</sub> = 6 Ω		11	17	ns
Rise Time	t <sub>r</sub>			10	15	
Turn-Off Delay Time	t <sub>d(off)</sub>			94	140	
Fall Time	t <sub>f</sub>			60	90	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -1.7 A, di/dt = 100 A/μs		55	80	

## Notes

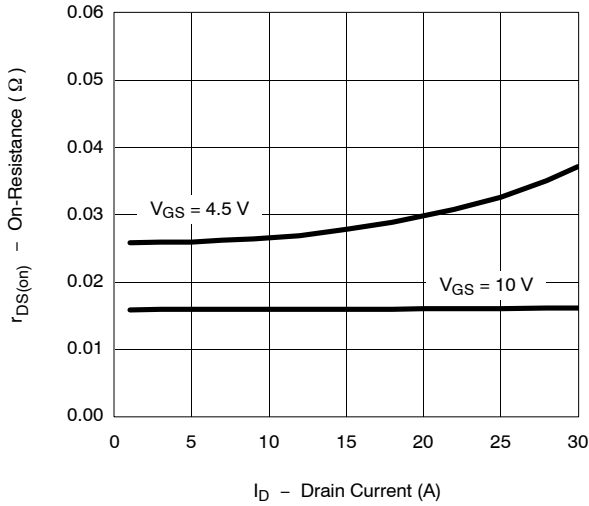
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.  
b. Guaranteed by design, not subject to production testing.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

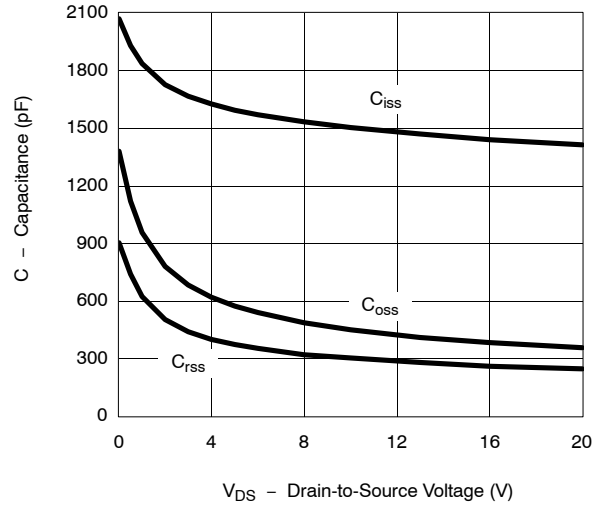


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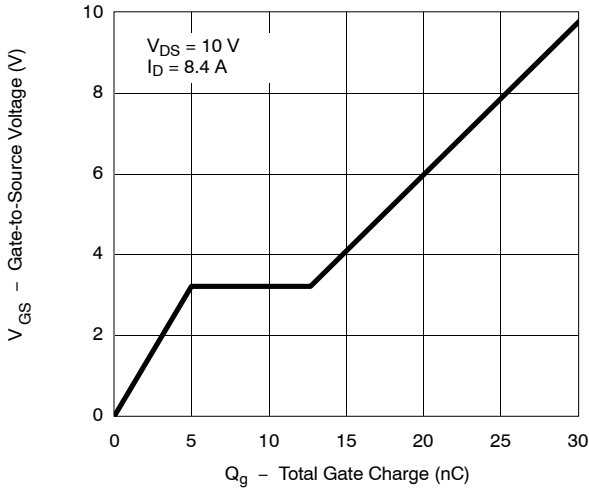
On-Resistance vs. Drain Current



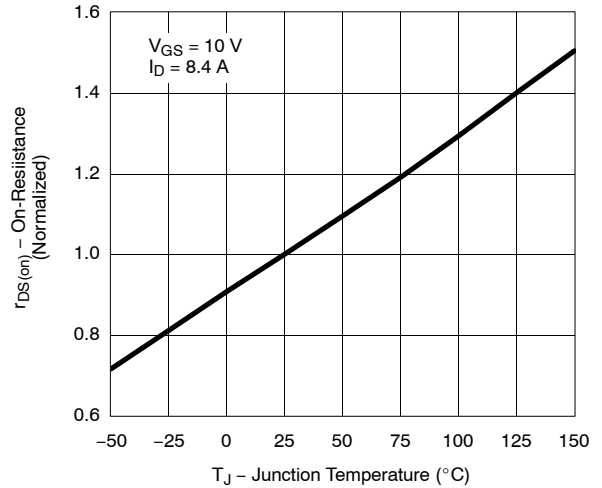
Capacitance



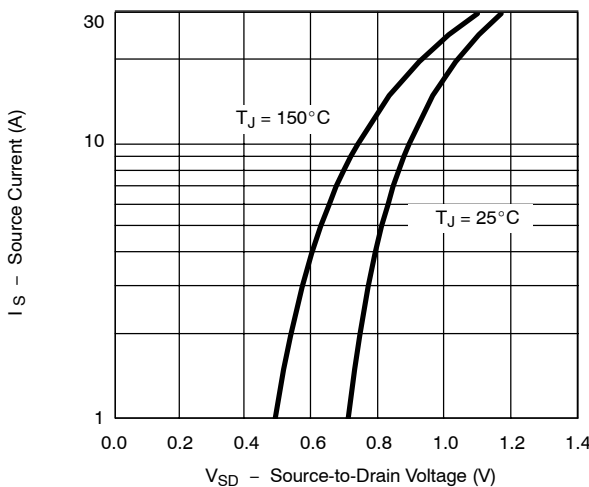
Gate Charge



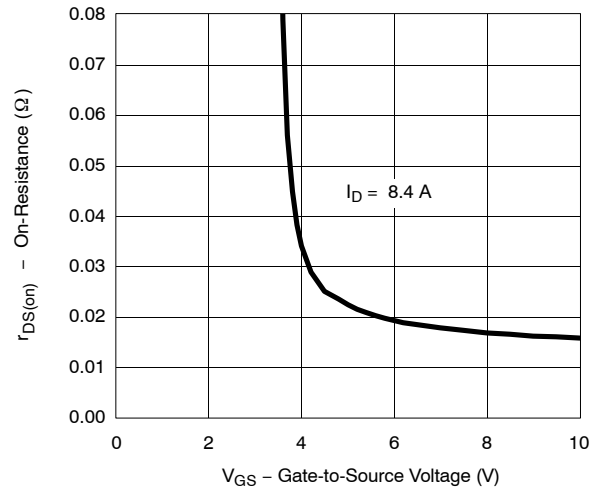
On-Resistance vs. Junction Temperature



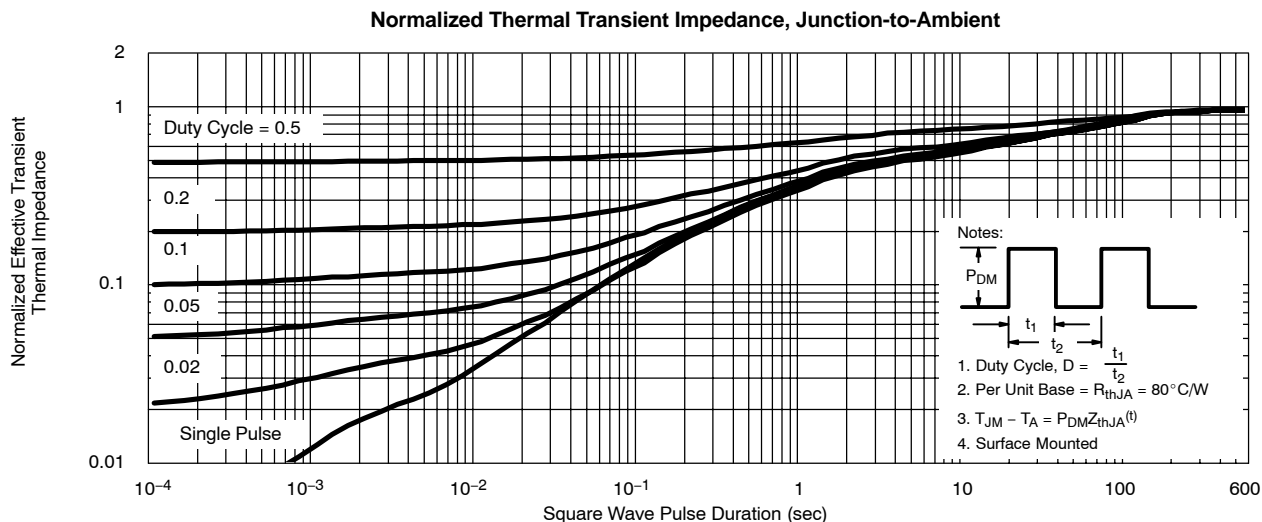
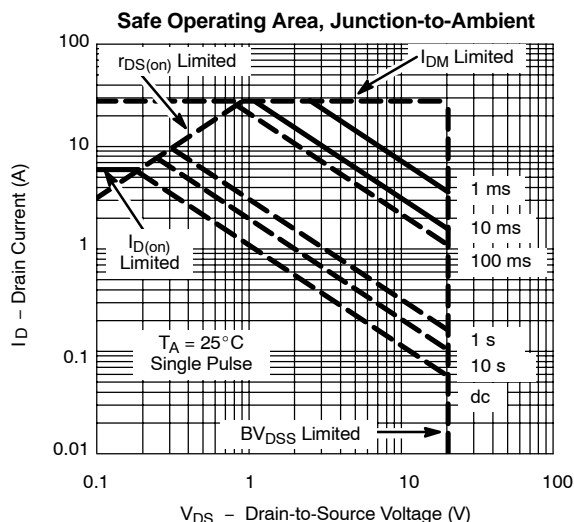
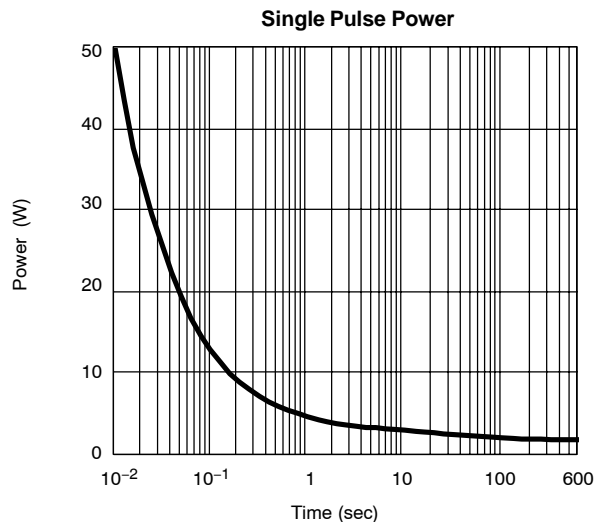
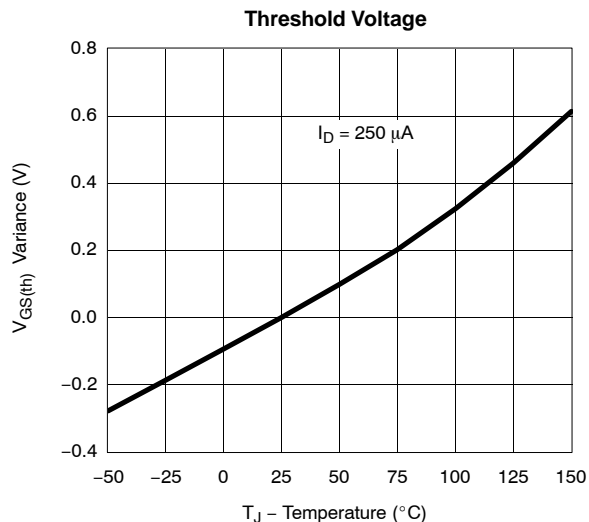
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**





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